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Amendments to Claims

1. (Cancelled).
2. (Currently Amended) The method of claim 1, wherein providing a metallic foil comprises:  
providing a foil comprising copper.
3. (Currently Amended) The method of claim 1, wherein forming at least one fiducial comprises: forming at least one fiducial comprising tungsten.
4. (Original) The method of claim 3, wherein the at least one fiducial is formed from a paste containing:  
glass; and  
tungsten in excess of 53% by weight.
5. (Original) The method of claim 3, wherein:  
a dried print thickness of the at least one fiducial is at least 15 microns.
6. (Currently Amended) The method of claim 1, wherein:  
forming at least one feature and forming at least one fiducial comprise at least one firing step.
7. (Currently Amended) The method of claim 1, wherein:  
forming at least one feature and forming at least one fiducial comprise curing of a thick-film polymer paste.
8. (Currently Amended) ~~The method of Claim 1~~ A method of making an innerlayer panel, comprising:  
providing a metallic foil;  
forming at least one fiducial over the foil;  
forming at least one feature over the foil;

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applying a dielectric over the at least one feature and over the at least one fiducial, thereby embedding the at least one fiducial and the at least one feature; and identifying the location of the at least one fiducial using X-rays,  
further comprising:

applying a second foil to the dielectric before identifying the location of the at least one fiducial;

forming at least one register hole in the innerlayer panel according to the identified location of the at least one fiducial;

positioning a photo-tool according to the location of the at least one register hole;

imaging the foils with the photo-tool; and

etching the foils, wherein etching results in terminations for the embedded at least one feature.

9. (Currently Amended) The method of claim 1 8, wherein:  
the at least one feature comprises at least one capacitor or resistor.
10. (Currently Amended) The method of claim 1 8, further comprising:  
applying an encapsulant over the at least one fiducial prior to applying the dielectric.
11. (Original) The method of claim 10, wherein: the dielectric is a prepreg.
12. (Withdrawn) A printed wiring board comprising a plurality of stacked innerlayer panels formed by the method of claim 1.
13. (Withdrawn) An innerlayer panel, comprising:  
a dielectric;  
at least one feature at least partially embedded within the dielectric;  
at least one fiducial at least partially embedded within the dielectric, the fiducial comprising at least one element selected from the group consisting of: tungsten, tantalum, gold, iridium, rhenium, osmium, uranium and platinum; and

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at least one conductive termination or associated circuitry in contact with the dielectric and electrically coupled to the at least one feature.

14. (Withdrawn) The innerlayer panel of claim 13, wherein:  
the at least one fiducial further comprises glass.
15. (Withdrawn) The innerlayer panel of claim 13, wherein:  
the at least one feature comprises at least one of a capacitor and a resistor.
16. (Withdrawn) The innerlayer panel of claim 13, further comprising:  
an encapsulant disposed between the at least one feature and the dielectric.
17. (Withdrawn) A printed wiring board comprising a plurality of stacked  
innerlayer panels of claim 13.